

# Characterization of Ultra-Fast Silicon Detectors (UFSD) for High Energy Physics Application



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#### **Ultra-Fast Silicon Detectors**

- Low Gain Avalanche Detector (LGAD) based technology.
- Thin-detectors (for fast signal processing
- Suitable candidate for 4D tracking
- CMS-ETL and ATLAS-HGTD will be using these detectors
- Applications in Particle Physics (particle identification), as well as in medical facilities (Positron Emission Tomography)

#### **Challenges**

- Detectors for Phase II upgrades (HL-LHC) ~ 30ps resolution
- Greater pile-up ~ 200

- Response of these LGADs are significantly fast (2 ns), which is why they are categorized as ultra-fast silicon detectors.
- Higher gain layer doping leads to higher charge collection, hence higher gain.
- Leakage current decrease by 1 order magnitude and  $V_{BD}$  increase with the decrease in temperature.

No dependence of temperature is observed on  $V_{\text{GL}}$ .

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Summary

- IR Laser (1064 nm) is used for the gain measurements. All measurement are carried out at same laser intensity, pulse width, and temperature
- Fig. 10 (a) shows the signal formation with bias voltage. After 40V, the signal is significantly faster i.e., charge carriers gets collected **within 2 ns**.
- The collected charge with in 2 ns is shown in Fig. 9 (c), for LGAD 16-31, 19-4 and PIN 16-30.

**Figure 2**: 2D scan (xy) of the PIN confirming the dimensions of the device.

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- Temperature dependent gain measurements and time-resolution measurements with be carried out in near future.
- Irradiation studies on these sensors is planned in future.

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#### **Future goals:**



### **Devices Under Test (DUT)**



**Figure 9**: (a) TCT setup at AGH University of Krakow, (b) Focusing of infrared laser (beam spot ~ 10µm), (c) Comparison of TCT waveforms illuminated by Red (658 nm) and IR (1064 nm) lasers, (d) Charge collection homogeneity in 50µm<sup>2</sup>.



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• Gain of the **LGAD 19-4 is ~5.5**, and for **LGAD 16-31 is ~5** at 150 V. The difference is due to higher gain layer doping in 19-4.

### Introduction



**Figure 1**: (a) Standard LGAD structure, (b) Device under

#### **Table 1**: Details of the devices used in this work





**Figure 10**: (a) Signal formation as a function of bias voltage of LGAD 16-31, (b) TCT waveform comparison of LGADs and PIN using IR laser, (c) Comparison of charge collection with in 2 ns (d) Gain calculation as a function of bias voltage.

### Electrical Characterizations: C-V

- We are equipped with TCT system with Red and IR lasers, manufactured by Particulars. The system can be seen in Fig. 9(a). Focused IR laser shows the beam spot **~ 10µm** as seen in Fig. 9 (b).
- A comparison based on the different wavelengths of illumination is made to observe if there is change in the signal shape as seen in Fig. 9 (c). The signal is too fast to show any changes caused by difference in wavelength penetration depth.
- In Fig. 9 (d), **charge collection homogeneity** is observed in 50µm<sup>2</sup> area of the device. The charge collection shows uncertainty within **±7%** of the mean value, referring to a homogenous charge collection.



## Laser Characterizations



#### **Conclusions**

- LGADs and PINs used in this worked are from 3331 wafer of **MediPix3** mask, manufactured by **Micron Semiconductors Ltd.**
- Difference in LGAD as compared to PIN is the additional **p<sup>+</sup>-implant (gain layer).**
- Device parameters are given in Table 1.

